



INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(51) International Patent Classification⁷ : H01L 31/0203, 33/00, 21/60	A1	(11) International Publication Number: WO 00/07247 (43) International Publication Date: 10 February 2000 (10.02.00)
(21) International Application Number: PCT/GB99/01970 (22) International Filing Date: 23 June 1999 (23.06.99) (30) Priority Data: 9816692.9 30 July 1998 (30.07.98) GB (71) Applicant (for all designated States except US): BOOKHAM TECHNOLOGY LIMITED [GB/GB]; 90 Milton Park, Abingdon, Oxfordshire OX14 4RY (GB). (72) Inventor; and (75) Inventor/Applicant (for US only): MAUND, Brigg [GB/GB]; Home Farm Cottage, 21a School Lane, Milton, Abingdon, Oxfordshire OX14 4EH (GB). (74) Agents: PALMER, Roger et al.; Page White & Farrer, 54 Doughty Street, London WC1N 2LS (GB).		(81) Designated States: AE, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, CA, CH, CN, CU, CZ, DE, DK, EE, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MD, MG, MK, MN, MW, MX, NO, NZ, PL, PT, RO, RU, SD, SE, SG, SI, SK, SL, TJ, TM, TR, TT, UA, UG, US, UZ, VN, YU, ZA, ZW, ARIPO patent (GH, GM, KE, LS, MW, SD, SL, SZ, UG, ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, CH, CY, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, GW, ML, MR, NE, SN, TD, TG). Published <i>With international search report.</i>

(54) Title: LEAD FRAME ATTACHMENT FOR OPTOELECTRONIC DEVICE**(57) Abstract**

An optoelectronic device is mounted on a planar substrate in electrical connection with solder bumps adjacent an edge of the substrate and connection to a lead frame is made by loading the edge of the substrate on a lead frame support with lead frame conductors in engagement with the solder bumps and applying heat to melt the solder.

